

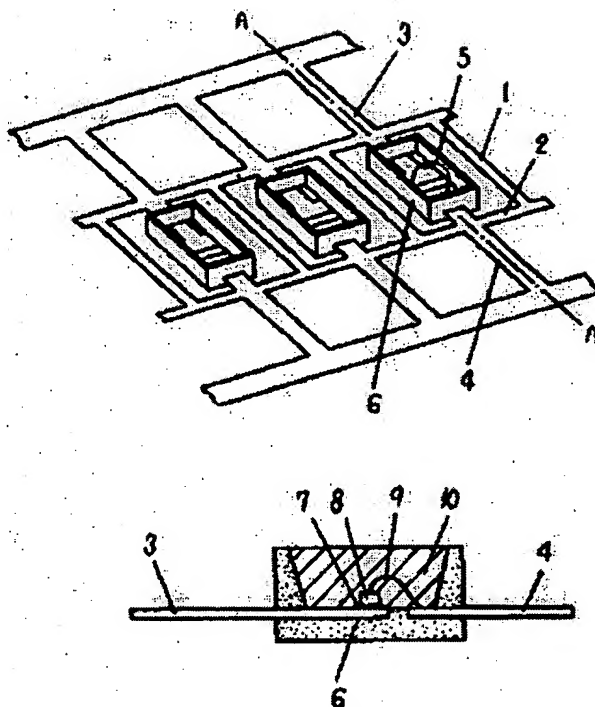
**ELECTRODE STRUCTURE FOR SEMICONDUCTOR DEVICE**

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**Abstract of JP58194382**

**PURPOSE:** To prevent the generation of plastic deformation by a method wherein a pair of metal electrode material, extending inwards facing each other, are formed in one body with the supporting member which is in parallel and crossed at right angle with said electrode materials, and the inner point part of said metal electrode materials is supported by an insulating frame body in a surrounding manner exposing the main surface.

**CONSTITUTION:** An insulated frame body 6, having a concavity opening upwards, is formed using an electric insulating material and electrode bodies 3 and 4 and a bonding pad part 5 are fixed in such a manner that the main surface will be exposed. According to this constitution, the unsatisfactory plastic deformation generated by external stress can be prevented, and the handling of material is simplified a great deal. Also, after the bonding pad part 5 has been fixed using an electric insulating material and when a light-emitting element chip 8 is placed through the intermediary of a conductive bonding material 7 and an electrode-connection is performed on the above using a fine metal wire 9, the mechanical stabilization and the handling workability thereof can be improved, while in the sealing process, a sealing enclosure can be formed by injecting and hardening light-transmitting epoxy resin 10 into the recess enclosed by an insulating frame body 5, thereby simplifying the seal-mold forming process.



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